



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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High Performance Dispensable Gap Filler Preliminary



TPUTTY[™] 607 DISPENSABLE GAP FILLER DESCRIPTION

Laird Tputty[™] 607 is a high thermally conductive single part dispensable material designed with automation and vertical stability in mind. Laird has leveraged its knowledge of thermally conductive fillers and resin systems to develop a single part dispensable that demonstrates reliability in a variety of application orientations.

Tputty[™] 607 is ideal for applications that can benefit from automation; and allows minimization of SKUs in applications with gap variability. In addition to providing application flexibility and variable gap adaptation, Tputty[™] 607 will exert minimal stress on your component while maintaining interface contact to maximize thermal transfer. Combined with Laird's global technical support and global footprint, deploying Tputty[™] 607 is easier than ever.

When it is time to integrate Tputty[™] 607 into your production environment, Laird can work with your existing dispensing partner or provide recommendations for a dispensing equipment provider.

FEATURES AND BENEFITS

- RoHS Compliant
- Complete Dispensing Solution Options Available
- 6.4 W/mK
- Demonstrated thermal cycling stability
- Low outgassing per ASTM E595
- Available in cartridges (75cc, 180cc, 360cc, 600cc) and pails (1 gallon and 5 gallon)

Packaging Size	Fill Volume	Fill Weight
75cc (2.5 oz)	56cc	193g
180cc (6 oz)	159cc	549g
360cc (12 oz)	326cc	1242g
600cc (20 oz)	601cc	2070g
1 gallon	3768cc	13kg
5 gallon	5797cc	20kg

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THR-DS-Tputty 607_Preliminary062817

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SPECIFICATIONS

(typical values)

PROPERTY	TYPICAL VALUE	METHOD
Construction	Ceramic filled silicone dispensable	N/A
Color	Blue	Visual
Thermal Conductivity (W/mK)	6.4	Hot Disk
Flow Rate (75cc taper tip, 0.125" orifice, 40 psi)	60 g/min	Laird Test Method – A16724-00
Density (g/cc)	3.45	Helium Pycnometer
Flammability	V-0 (pending)	UL 94
Temperature Range	-40 to 150°C	Laird Test Method
Outgassing TML (weight %)	0.204	ASTM E595
Outgassing CVCM (weight %)	0.01	ASTM E595
Dielectric Breakdown	>6000 VAC (at 40 mil)	ASTM D149
Dielectric Constant @ 1MHz	15.0	ASTM D150
Minimum Bond line Thickness	0.150 mm (0.006")	Laird Test Method - A16112-00
Volume Resistivity (ohm-cm)	10 ¹³	ASTM D257

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